

S/N 10/722,838

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Suan J. Boon

Examiner: James Mitchell

Serial No.: 10/722,838

Group Art Unit: 2813

Filed: November 26, 2003

Docket No.: 303.601US3

Customer No.: 73115

Confirmation No.: 8165

Title: METHOD OF PACKAGING AT A WAFER LEVEL USING AN ADHESIVE (as amended)

AMENDMENT & RESPONSE UNDER 37 C.F.R. § 1.111

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In response to the Office Action mailed June 27, 2008, please amend the application as follows: